

ABSTRACT

A heat sink assembly of the present invention includes a printed circuit board (10), a retention module (20), four pins (30), a heat sink (40) and a clip (50). The printed circuit board has an electronic package (100) mounted thereon. The retention module is integrally formed, substantially rectangular, and has a symmetrical configuration. The retention module defines an openings (26) therein for surrounding the electronic package. Four positioning holes (28) are defined in four corners of the retention module. In assembly of the heat sink assembly, the pins are interferentially positioned in the positioning holes of the retention module. Portions of the pins extending out beyond the retention module are welded to the printed circuit board. The clip cooperates with the retention module to press the heat sink against the electronic package.